

Abstract of the Disclosure

~~In a socket used to house semiconductor die during testing, a recessed socket~~
contact is provided that avoids pinching the die's contacts. Also provided are socket
5 contacts that allow for smaller socket holes and, therefore, denser arrays of socket
contacts. In one embodiment, the body of the socket contact comprises a head, a spring
coupled to the head, and a shaft coupled to the spring; no outer shell is needed for the
spring, as the non-conductive sides of the socket hole serve that function. In another
embodiment, the body of the socket contact comprises a metal shaft having an aperture.
10 Compression causes the shaft to close around the slit, thereby decreasing the amount of
lateral buckling. In yet another embodiment, semiconductor fabrication techniques are
~~used to construct a dense array of contacts.~~